

AMENDMENT UNDER 37 C.F.R. § 1.111
U.S. APPLN. NO.: 09/735,892

✓
Please add new claim 5 as follows:

A2
Sub B2
5. (New) A semiconductor wafer processing method, comprising adhering the removable pressure-sensitive adhesive sheet of claim 1 to a front or back surface of the wafer, and processing the wafer.